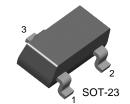


MMBT3646

Switching Transistor



1. Base 2. Emitter 3. Collector

Absolute Maximum Ratings $T_C=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Value	Units	
V _{CEO}	Collector-Emitter Voltage	15	V	
V _{CES}	Collector-Emitter Voltage	40	V	
V _{CBO}	Collector-Base Voltage	40	V	
V _{EBO}	Emitter-Base Voltage	5		
I _C	Collector Current (DC) - Continuous	300	mA	
P _D	Total Device Dissipation @ T _A =25°C - Derate above 25°C	625 5	mW mW/°C	
T _J , T _{STG}	Operating and Storage Junction Temperature Range	150	°C	

Electrical Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Min.	Тур.	Max.	Units
Off Characte	eristics				
V _{(BR)CES}	Collector-Emitter Breakdown Voltage (I _C = 100μAdc, V _{BE} = 0)	40			V
V _{CEO(sus)}	Collector-Emitter Sustaining Voltage (1) (I _C = 10mAdc, I _B = 0)	15			V
V _{(BR)CBO}	Collector-Base Breakdown Voltage (I _C = 100μAdc, I _E = 0)	40			V
V _{(BR)EBO}	Emitter-Base Breakdown Voltage (I _E = 100μAdc, I _C = 0)	5			V
I _{CES}	Collector Cut-off Current (V _{CE} = 20Vdc, V _{BE} = 0)			0.5	μΑ
	$(V_{CE} = 20Vdc, V_{BE} = 0, T_A = 65^{\circ}C)$			3	
On Characte	eristics (1)	_			
h _{FE}	DC Current Gain (I _C = 30mAdc, V _{CE} = 0.4Vdc)	30		120	
	$(I_C = 100 \text{mAdc}, V_{CE} = 0.5 \text{Vdc})$	25			
	$(I_C = 300 \text{mAdc}, V_{CE} = 1 \text{Vdc})$	15			
V _{CE(sat)}	Collector-Emitter Saturation Voltage (I _C = 30mAdc, I _B = 3mAdc)			0.2	V
()	$(I_C = 100 \text{mAdc}, I_B = 10 \text{mAdc})$			0.28	
	$(I_C = 300 \text{mAdc}, I_B = 30 \text{mAdc})$			0.5	
	$(I_C = 30\text{mA}, I_B = 3\text{mA}, T_A = 65^{\circ}\text{C})$			0.3	
V _{BE(sat)}	Base-Emitter Saturation Voltage (I _C = 30mAdc, I _B = 3mAdc)	0.73		0.95	V
()	$(I_C = 100 \text{mAdc}, I_B = 10 \text{mAdc})$			1.2	
	$(I_C = 300 \text{mAdc}, I_B = 30 \text{mAdc})$			1.7	

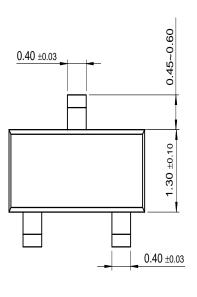
Symbol	Parameter			Тур.	Max.	Units
Small-Signal	Characteristics					
C _{obo}	Output Capacitance ($V_{CE} = 5Vdc, I_E = 0, f = 1MHz$)				5	pF
C _{ibo}	Input Capacitance (V _{EB} = 0.5Vdc, I _C = 0, f = 1MHz)				8	pF
Switching Ch	aracteristics					
t _{on}	Turn-On Time	$V_{CC} = 10Vdc$, $I_{C} = 300mAdc$,			18	ns
t _d	Delay Time	$I_{B1} = 30 \text{mAdc}, V_{CE(off)} = 3 \text{V}$			10	ns
t _r	Rise Time				15	ns
t _{off}	Turn-Off Time	$V_{CC} = 10Vdc$, $I_C = 300mAdc$,			28	ns
t _f	Fall Time	$I_{B1} = I_{B2} = 30$ mAdc			15	ns
t _s	Storge Time				20	ns

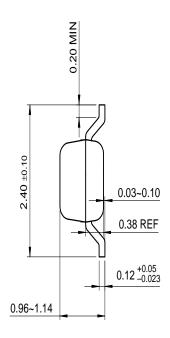
Thermal Characteristics

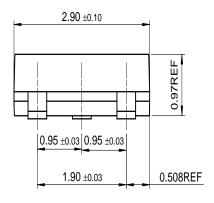
Symbol	Parameter	Min.	Тур.	Max.	Units
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient			200	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case			83.3	°C

Package Dimensions

SOT-23







Dimensions in Millimeters

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Programmable Ad	ctive Droop™	OPTOPLANAR™	SMART START™	

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